NEWS Letter

Jan 2025

JEPPIAAR INSTITUTE OF TECHNOLOGY

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DEPARTMENT OF ECE

Jan 2025

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DEPARTMENT NEWS

DEPARTMENT OF ECE

MOU SIGNING

MoU Signing Ceremony with Industry Partners

The Department of Electronics and Communication Engineering, Jeppiaar Institute of Technology, successfully organized the Memorandum of Understanding (MoU) Signing Ceremony with Evolve Innovations and Global Consulting Services on 6th January 2026 at 10:30 AM. This significant collaboration aims to strengthen industry–academia interaction, promote innovation-driven learning, and provide students with enhanced exposure to real-time industrial practices, emerging technologies, internships, training programs, and collaborative research opportunities.

The MoU was signed in the esteemed presence of the Chief Patron, Dr. N. Marie Wilson, Chairman, whose visionary leadership continues to inspire academic excellence and innovation. The event was graced by the Patrons, Dr. J. Venu Gopala Krishnan, Principal, and Dr. S. Shenbaga Ezhil, IQAC Director, whose guidance emphasized the importance of industry partnerships for holistic student development. The program was led by the Head of the Department, Dr. Sripriya T, Associate Professor, Department of ECE, and coordinated by Dr. Benisha M, Assistant Professor, Department of ECE, Faculty Coordinator. Faculty members and students of the department actively participated in the event.

This MoU aligns with the institution's commitment to innovation, skill development, and sustainable growth, and strongly supports the objectives of NEP 2020 and Sustainable Development Goals (SDGs) by fostering quality education, industry innovation, and partnerships for development. The Department looks forward to fruitful outcomes from this collaboration, paving the way for skill enhancement, entrepreneurial initiatives, and research advancements for the benefit of students and faculty members.


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COLLABRATIVE WORKSHOP ON INNOVATE INDIA EMERGING CAREERS IN ENTREPRENEURSHIP & TECHNOLOGY

The Department of Electronics and Communication Engineering, Jeppiaar Institute of Technology, in collaboration with IEEE and the Institution's Innovation Council (IIC), successfully organized a Collaborative Workshop on "Innovate India: Emerging Careers in Entrepreneurship & Technology" on 6th January 2026, from 10:00 AM to 11:00 AM.

The workshop featured eminent industry experts Mr. Gnanasekar Dhanapal, Strategy Head – Digital Operations, and Mr. Susheendran Karthick CG, CEO & Project Head. The speakers shared valuable insights on innovation-driven entrepreneurship, digital transformation, startup ecosystems, and emerging career opportunities in technology.

The session highlighted the importance of entrepreneurial mindset, industry-relevant skills, and innovation in shaping successful careers, encouraging students to explore startups, product development, and technology-based enterprises.

The program was organized under the leadership of Dr. T. Sripriya, Head of the Department, ECE, with Mr. M. Sudhagar, Assistant Professor, ECE, serving as the Faculty Coordinator. The event was efficiently coordinated by the student coordinators D. Usharani and M. Janani.

The workshop witnessed enthusiastic participation from students and faculty members and contributed significantly to enhancing awareness of emerging career paths aligned with Make in India and Innovate India initiatives, fostering innovation and professional growth.


JEPPIAAR

RESEARCH METHODOLOGY EVENT ON INNOVATION CENTRIC RESEARCH FOR PATENTS, PRODUCTS, AND PUBLICATIONS

The Department of Electronics and Communication Engineering, Jeppiaar Institute of Technology, in association with IEEE, Institution's Innovation Council (IIC), and AICTE IDEA Lab, successfully organized a Research Methodology Event on "Innovation-Centric Research for Patents, Products, and Publications" on 7th January 2026, from 12:30 PM to 1:30 PM, at LH-14.The session was delivered by Mr. K. Raguvaran, Mentor, Electronic Hardware Designer, Consultant, Entrepreneur, and Technical Guru, AICTE IDEA Lab. The resource person provided in-depth insights into structured research methodologies, innovation-driven problem identification, patent filing processes, product development strategies, and quality research publications.

The event emphasized the importance of transforming research ideas into intellectual property, viable products, and impactful publications, motivating students and faculty to pursue applied and industry-oriented research. The program was organized under the leadership of Dr. T. Sripriya, Head of the Department, ECE, and coordinated by Dr. W. Nancy, Assistant Professor, ECE, with active support from the student coordinator Ajoe Blessy A (III-ECE). The session witnessed enthusiastic participation from students and faculty members. The event significantly contributed to strengthening the research culture of the department and aligned with the institution's vision of innovation, entrepreneurship, and sustainable academic excellence.


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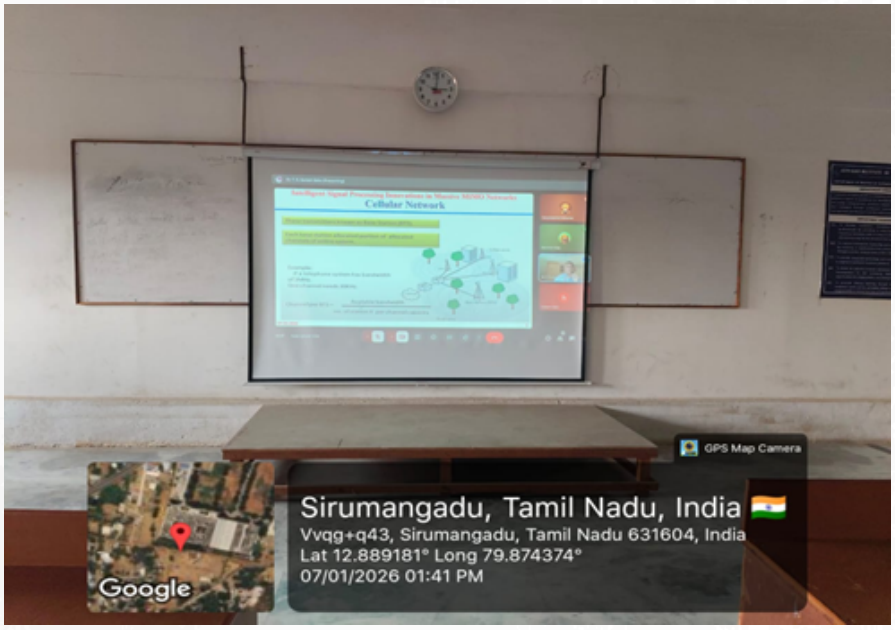
SEMINAR ON INTELLIGENT SIGNAL PROCESSING INNOVATIONS IN MASSIVE MIMO NETWORKS

The Department of Electronics and Communication Engineering, Jeppiaar Institute of Technology, successfully organized a seminar on "Intelligent Signal Processing Innovations in Massive MIMO Networks" on 7th January 2026, from 1:30 PM to 2:30 PM. The seminar was delivered by Dr. T. N. Suresh Babu, Assistant Professor, Department of ECE, Adhiparasakthi Engineering College. The resource person provided valuable insights into advanced signal processing techniques, intelligent algorithms, and their applications in Massive MIMO systems, which play a vital role in 5G and next-generation wireless communication networks.

The session highlighted recent research trends, challenges, and innovations in Massive MIMO technology, enabling students to understand the practical significance of intelligent signal processing in high-capacity and energy-efficient communication systems. The event was organized under the guidance of the Chief Patron, Dr. N. Marie Wilson, Chairman, and the Patrons, Dr. J. Venu Gopala Krishnan, Principal, and Dr. S. Shenbaga Ezhil, IQAC Director. The program was led by Dr. T. Sripriya, Head of the Department, ECE, and coordinated by the faculty coordinators Ms. Karthika T and Ms. Hubert Mary L, Assistant Professors, ECE. The seminar witnessed active participation from students and faculty members and significantly enhanced awareness of emerging technologies in wireless communications and intelligent signal processing, contributing to academic and research excellence.


Cellular Network
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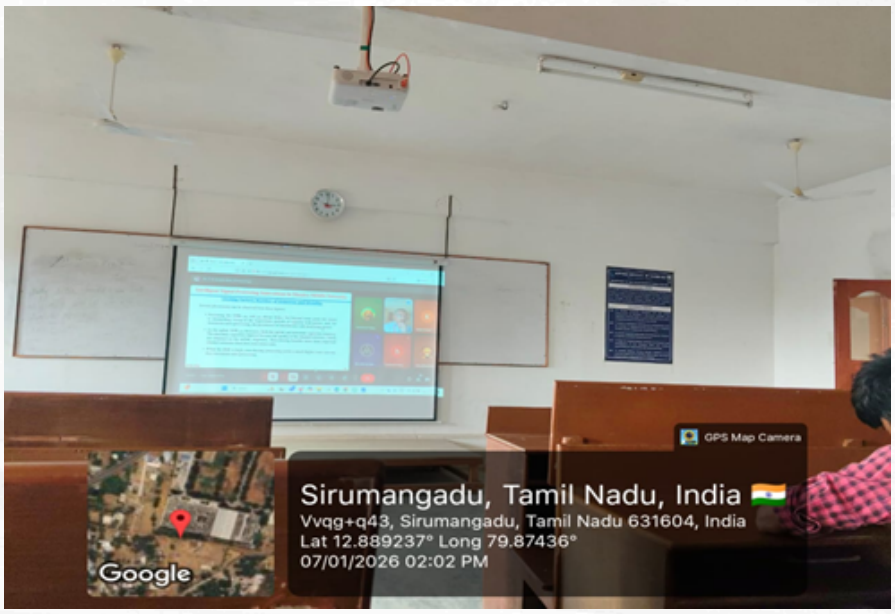
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SEMINAR ON ADAPTIVE FILTERS FOR EMERGING INNOVATIVE APPLICATIONS

INSTITUTION'S INNOVATION COUNCIL- IIC 8.0

In Association with

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

MoE's INNOVATION CELL (GOVERNMENT OF INDIA) IEEE Advancing Technology for Humanity

Presents

INSTITUTION'S INNOVATION COUNCIL

Seminar on Adaptive Filters for Emerging Innovative Applications

Dr.A.MANIMARAN
Professor/ECE
Karpaga Vinayaga College of Engineering and Technology

DATE: 30.01.2026 TIME: 10.30 AM VENUE: LH 6

JIT JEPPIAAR INSTITUTE OF TECHNOLOGY (AN AUTONOMOUS INSTITUTION)

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The Institution's Innovation Council (IIC 8.0), in association with the Department of Electronics and Communication Engineering, organized a technical seminar titled "Adaptive Filters for Emerging Innovative Applications" on 30 January 2026 at LH-6, Jeppiaar Institute of Technology.

The session was delivered by Dr. A. Manimaran, Professor, Department of ECE, Karpaga Vinayaga College of Engineering and Technology. The seminar provided valuable insights into the fundamentals and advanced concepts of adaptive filtering techniques and their significance in modern engineering applications.

Dr. Manimaran elaborated on the working principles of adaptive filters and discussed their applications in areas such as noise cancellation, signal enhancement, system identification, biomedical signal processing, and emerging communication systems. The session emphasized how adaptive filtering plays a crucial role in solving real-time signal processing challenges and supports innovation in next-generation technologies.

The seminar was highly informative and interactive, encouraging students to explore adaptive signal processing as a potential research and innovation domain. Faculty members and students actively participated, making the event a great success under the initiatives of IIC and the ECE department.


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Sriperumbudur, Kancheepuram, Tamil Nadu 631604, India
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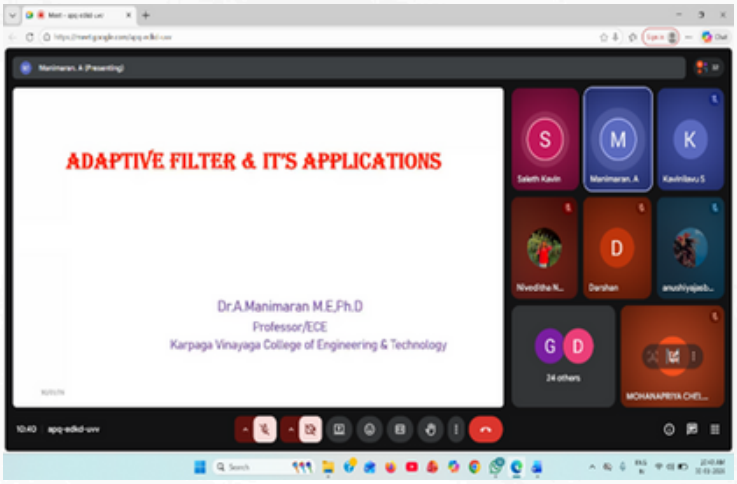
ADAPTIVE FILTER & IT'S APPLICATIONS
Dr.A.Manimaran M.E,Ph.D
Professor/ECE
Karpaga Vinayaga College of Engineering & Technology


DIGITAL SIGNAL PROCESSING
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DAC
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Digital System
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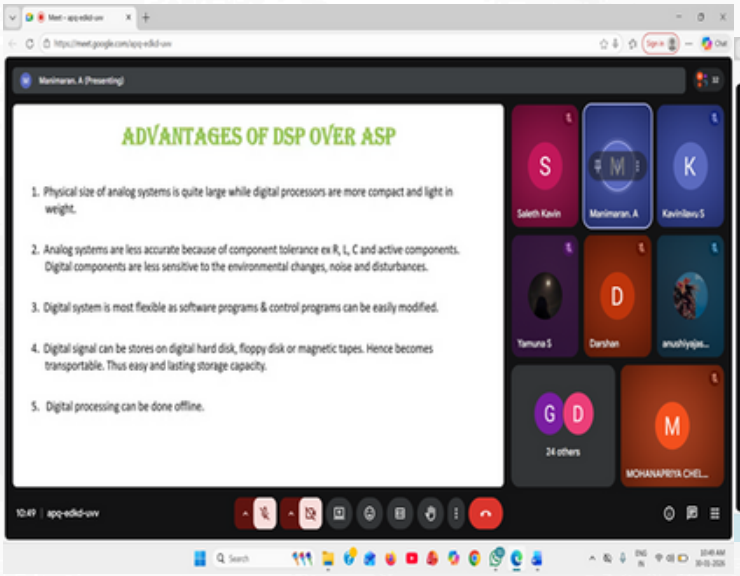
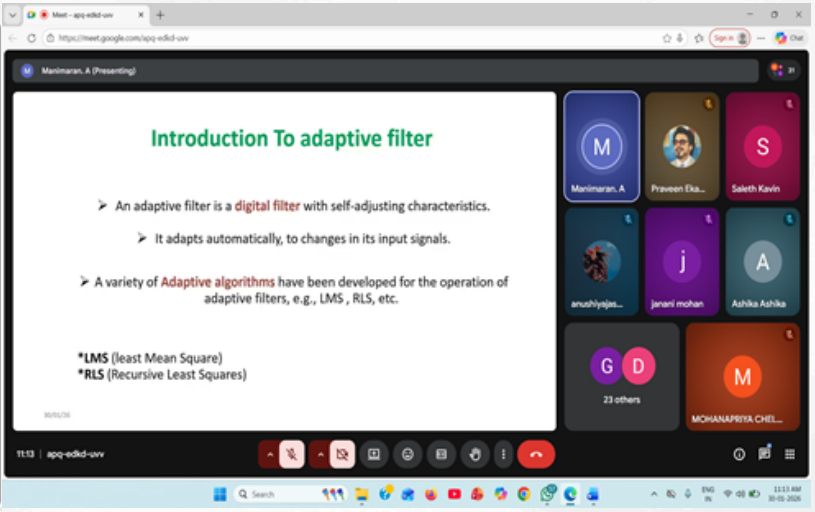

ADVANTAGES OF DSP OVER ASP
1. Physical size of analog systems is quite large while digital processors are more compact and light in weight.
2. Analog systems are less accurate because of component tolerance ex R, L, C and active components. Digital components are less sensitive to the environmental changes, noise and disturbances.
3. Digital system is most flexible as software programs & control programs can be easily modified.
4. Digital signal can be stores on digital hard disk, floppy disk or magnetic tapes. Hence becomes transportable. Thus easy and lasting storage capacity.
5. Digital processing can be done offline.


Introduction To adaptive filter
An adaptive filter is a digital filter with self-adjusting characteristics.
It adapts automatically, to changes in its input signals.
A variety of Adaptive algorithms have been developed for the operation of adaptive filters, e.g., LMS , RLS, etc.
*LMS (least Mean Square)
*RLS (Recursive Least Squares)

STUDENT ARTICLE

CURRENT TRENDS IN ELECTRONICS & COMMUNICATION

Ransom Rinu.B

III Year - ECE

Artificial Intelligence (AI) in Electronics and Communication Engineering

Artificial Intelligence (AI) has become one of the most influential trends in the field of Electronics and Communication Engineering (ECE). It is transforming how electronic systems are designed, how communication networks operate, and how data is processed and transmitted.

Role of AI in Electronics

In modern electronics, AI is embedded directly into hardware systems through AI-enabled chips and processors. These smart chips can analyze data, recognize patterns, and make decisions without depending entirely on cloud computing. This reduces delay, power consumption, and improves system efficiency.

Examples include:

· Smart sensors that detect faults automatically

· AI-based embedded systems in medical devices

· Intelligent consumer electronics like smartphones and wearables

· AI also helps in VLSI design and testing, where machine learning algorithms optimize circuit layouts, detect errors, and reduce design time.

AI in Communication Systems

AI plays a crucial role in improving the performance of wireless and wired communication networks. Traditional communication systems rely on fixed algorithms, but AI-based systems can learn and adapt in real time.

Key applications include:

- Network optimization – AI manages traffic, reduces congestion, and improves data speed
- Signal processing – AI improves noise reduction, modulation, and channel estimation
- 5G and future 6G networks – AI enables ultra-low latency, smart spectrum allocation, and self-healing networks
- AI is also used in telecommunication security, where it detects fraud, intrusion, and abnormal network behavior.

Edge AI and IoT Integration

With the growth of the Internet of Things (IoT), AI is increasingly implemented at the edge (near the data source). Edge AI allows devices to process data locally instead of sending everything to the cloud.

Benefits:

- Faster response time
- Reduced bandwidth usage
- Improved data privacy
- This is especially useful in smart cities, industrial automation, autonomous vehicles, and healthcare monitoring systems.

Advantages of AI in ECE

- Higher efficiency and accuracy
- Reduced human intervention
- Intelligent decision-making
- Better utilization of communication resources

Future Scope

AI is expected to be a core component of future electronic and communication systems. Areas like autonomous communication networks, intelligent antennas, quantum communication support systems, and AI-driven semiconductor design will create vast opportunities for ECE engineers.

Conclusion

Artificial Intelligence is no longer optional in Electronics and Communication Engineering—it is essential. By combining intelligent algorithms with electronic hardware and communication systems, AI is shaping faster, smarter, and more reliable technologies for the future.

Sahaya Shalon A S

III Year - ECE

6G TECHNOLOGY – THE FUTURE OF WIRELESS COMMUNICATION

6G technology represents the next generation of wireless communication, expected to transform the way people, devices, and systems interact. While 5G has introduced high-speed connectivity and low latency, 6G aims to achieve ultra-high data rates, near-zero latency, massive device connectivity, and intelligent network automation.

One of the most significant features of 6G is the use of terahertz (THz) frequency bands, which allow extremely fast data transmission far beyond current wireless standards. This advancement will enable next-generation applications such as holographic communication, extended reality (XR), digital twins, autonomous transportation, and real-time remote medical procedures.

Artificial Intelligence is expected to play a central role in 6G networks. Unlike previous generations, 6G systems will be AI-native, meaning that AI will be embedded directly into the network architecture. AI-driven communication systems will support self-learning, self-optimizing, and self-healing networks, resulting in improved efficiency, reliability, and security.

From an Electronics and Communication Engineering (ECE) perspective, 6G opens vast opportunities in research and innovation. ECE engineers will contribute to areas such as advanced antenna design, high-frequency circuit development, intelligent signal processing, semiconductor technology, and energy-efficient communication systems. The integration of AI with communication hardware and software will further expand the scope of ECE applications.

Global research institutions, governments, and industries have already started investing in 6G development to support future smart cities, autonomous systems, and intelligent digital infrastructure. As technology continues to evolve, 6G is expected to become the backbone of a fully connected and intelligent world.

In conclusion, 6G technology marks a major milestone in the evolution of wireless communication. Staying updated with 6G concepts and advancements will enable ECE students and professionals to be well-prepared for future challenges and contribute meaningfully to next-generation communication systems.

NANDHIKA.A

II YEAR - ECE

Edge AI Hardware: The New Frontier of Electronics & Communication Engineering:

In recent years, artificial intelligence has quietly moved from cloud servers into our everyday devices. What makes 2026 different is that AI is no longer just a software story - it has become a hardware revolution, and Electronics & Communication Engineering sits right at the center of it.

The biggest shift happening now is the rise of Edge AI hardware. Instead of sending data to distant cloud servers for processing, modern devices are learning to think locally. Smartphones, drones, medical wearables, autonomous vehicles, and smart cameras are being designed to process information on the device itself. This reduces latency, improves privacy, saves bandwidth, and allows systems to operate even without constant internet connectivity. For ECE engineers, this change has opened a completely new design challenge: how to build intelligent systems that are both powerful and energy-efficient.

Traditional processors were never designed for AI workloads. Running neural networks on general-purpose chips wastes energy and limits performance. To solve this, engineers are now designing specialized AI accelerators that combine digital logic, analog computation, and optimized memory architectures. These chips are purpose-built for matrix operations, pattern recognition, and real-time decision-making. The design process requires deep knowledge of VLSI, embedded systems, signal processing, and communication protocols — all core areas of ECE.

What makes Edge AI especially exciting is the push toward ultra-low-power intelligence. Devices like health monitors and environmental sensors must run for months or even years on tiny batteries. Engineers are exploring new circuit techniques, near-threshold computing, and energy-harvesting systems to make this possible. Some research labs are even experimenting with neuromorphic hardware — chips inspired by the human brain — to perform complex AI tasks using a fraction of the power consumed by conventional processors.

Communication engineering also plays a crucial role in this ecosystem. Edge devices are not isolated; they operate in networks. Efficient wireless protocols, 6G-ready communication standards, and intelligent data compression are essential to allow billions of smart devices to interact seamlessly. The boundary between hardware design and communication systems is becoming increasingly blurred, forcing engineers to think in terms of integrated platforms rather than separate subsystems.

From an industry perspective, Edge AI is reshaping career opportunities. Companies are actively seeking engineers who understand both hardware and intelligent algorithms. Roles in embedded AI, AI chip design, sensor fusion, robotics, and smart infrastructure are growing rapidly. Unlike earlier waves of software-driven AI, this phase demands strong fundamentals in electronics, making ECE graduates uniquely positioned to lead the field.

Looking ahead, Edge AI is not just an upgrade — it represents a philosophical change in how technology is built. Intelligence is moving closer to the physical world. Devices are becoming autonomous, responsive, and context-aware. For Electronics & Communication Engineering, this marks a transition from supporting digital systems to creating intelligent hardware ecosystems.

In many ways, 2026 may be remembered as the year when AI truly became embedded into electronics — not as an add-on feature, but as a core design principle. And for the next generation of ECE engineers, this is less a trend and more a long-term transformation of the discipline itself.

PRADEEPAN S

II YEAR ECE

ORGANIC AND FLEXIBLE ELECTRONICS

Organic and flexible electronics have made remarkable progress in recent years, driven by innovations in materials science and electrical engineering. Researchers are developing advanced organic semiconductors, including π-conjugated polymers and small molecules, with improved charge mobility, mechanical flexibility, and environmental stability. Molecular engineering, side-chain modification, and donor–acceptor design strategies are enabling precise control of electronic properties, allowing devices to operate efficiently even when bent or stretched. These materials are foundational for next-generation flexible transistors, sensors, and wearable electronic devices.

Organic thin-film transistors (OTFTs) and organic electrochemical transistors (OECTs) are at the forefront of flexible device architectures. OTFTs are being optimized for low-cost, large-area printing, while OECTs offer low-voltage operation and high transconductance, making them ideal for integration with soft, conformal substrates in bioelectronic applications. Recent studies have also explored hybrid devices that combine organic materials with 2D materials like graphene, MoS_2, and MXenes to enhance electrical performance, mechanical robustness, and sensing capabilities in flexible electronics.

Advances in fabrication techniques have played a key role in bringing flexible electronics closer to commercialization. Additive manufacturing methods, such as inkjet printing, screen printing, and laser-assisted patterning, now allow high-resolution, metal-free device fabrication on a variety of substrates, including plastics, textiles, and biodegradable polymers. These approaches reduce manufacturing costs and energy consumption while enabling scalable production of large-area flexible circuits for wearable devices, sensors, and displays.

Mechanical reliability remains a central challenge for flexible electronics. Devices must maintain performance under repeated bending, stretching, and twisting. To address this, engineers are developing strain-tolerant interconnects, micro-patterned designs, and encapsulation strategies that prevent cracks and preserve electrical stability. Understanding the relationship between mechanical deformation and electronic properties is critical for ensuring long-term durability in applications such as wearable health monitors and foldable displays.

Sustainability is becoming increasingly important in the field. Researchers are exploring eco-friendly, recyclable, and biodegradable materials to reduce the environmental impact of flexible electronics. Innovations include fluorine-free ferroelectric polymers, biopolymers such as cellulose and silk fibroin, and closed-loop recycling methods for organic conductors and dielectrics. These approaches aim to minimize e-waste while maintaining device performance and biocompatibility, particularly in wearable and medical electronics.

Applications of organic and flexible electronics are expanding rapidly. Flexible displays, smart textiles, soft robotics, low-power IoT devices, and health-monitoring wearables are all benefiting from the unique combination of mechanical flexibility, lightweight design, and electrical functionality. Integration with the human body through skin patches, textile-based electronics, and conformal bio interfaces demonstrates the potential of these materials to transform consumer electronics, healthcare, and human–machine interaction technologies. Overall, organic and flexible electronics represent a transformative area in Electrical and Communication Engineering. By combining advanced materials, innovative device architectures, scalable fabrication, and sustainable design, the field is moving toward commercially viable, high-performance, and environmentally resp

Overall, organic and flexible electronics represent a transformative area in Electrical and Communication Engineering. By combining advanced materials, innovative device architectures, scalable fabrication, and sustainable design, the field is moving toward commercially viable, high-performance, and environmentally responsible electronics for a wide range of emerging applications.

Applying Design thinking to analyze the impact of Deadlock system throughput and resource utilization in concurrent systems

DATE: 16.12.2025 **EVENET NAME: SEMINAR**

The Department of Computer Science and Engineering hosted an Online Seminar on “Applying Design Thinking to analyze the impact of Deadlock system throughput and resource utilization in concurrent systems" with the objective of helping students understand how design thinking methodologies can be applied to analyze and address complex challenges in concurrent computing systems. The seminar began with an introduction to the fundamentals of concurrent systems, explaining how multiple processes compete for shared resources and how deadlocks can occur. Design thinking principles were then applied to deadlock scenarios by focusing on empathy towards system users and administrators, clearly defining system bottlenecks, ideating innovative strategies to reduce deadlock occurrences, and evaluating solutions based on throughput and resource efficiency.

PROGRAM TITLE: Design Thinking: Team up and Think Out

EVENT NAME : SEMINAR DATE: 17.12.2025

The Department of Computer Science and Engineering hosted a Design thinking Event, at Jeppiaar Institute of Technology on a seminar titled "Design Thinking: Team Up and Team Out" was conducted in our college with the aim of introducing students to the concept of design thinking and its importance in collaborative problem-solving. The session focused on nurturing innovation, creativity, and teamwork among students, helping them understand how structured thinking can lead to effective solutions in real-world scenarios. The seminar began with an introduction to design thinking as a user-centric approach to solving problems. The speaker explained the key stages of design thinking empathizing with users, defining problems clearly, ideating creative solutions, developing prototypes, and testing outcomes. Emphasis was placed on how this approach encourages students to think beyond conventional methods and adopt a more practical and innovative mindset.

COMPANY NAME: AMIZHTH TECHNO SOLUTION PRIVATE LIMITED

EVENT NAME: MOU COLLABORATION DATE: 17.12.2025

The Department of Computer Science, Jeppiaar Institute of Technology, successfully organized a Signing Ceremony for Industry & Institute Collaboration through a Memorandum of Understanding (MoU) with Amizhth Techno Solutions Private Limited, Madurai. The ceremony was held on Wednesday, 17th December 2025, at the Jeppiaar Institute of Technology campus, Kunnam, Sunguvarchatram. The event marked a significant step toward strengthening industry–academia partnerships and enhancing practical exposure for students. The MoU aims to promote collaborative activities such as industry training, internships, workshops, expert lectures, skill development programs, and joint initiatives that will bridge the gap between academic learning and industry requirements. This collaboration is expected to provide students with hands-on experience, real-time project exposure, and improved employability skills.

PROGRAM TITLE: Start-up-Driven Cloud Computing and Virtualization. Hands-On Workshop

EVENT NAME : WORKSHOP

DATE: 18.12.2025

The Department of Computer Science and Engineering hosted a one-day hands-on workshop, at Jeppiaar Institute of Technology "Startup-Driven Cloud Computing and Virtualization. Hands-On Workshop" on to provide participants with practical exposure to modern cloud technologies that power today's startup ecosystem. The workshop aimed to bridge the gap between theoretical knowledge and real-world implementation by focusing on how startups leverage cloud computing and virtualization to build scalable, cost-effective, and resilient solutions. The session began with an overview of cloud computing fundamentals, including service models such as IaaS, PaaS, and SaaS, and deployment models like public, private, and hybrid clouds. Emphasis was placed on how startups use cloud platforms to reduce infrastructure costs, accelerate product development, and scale applications dynamically based on demand. A major highlight of the workshop was the hands-on training in virtualization concepts. Participants worked with virtual machines and learned how virtualization enables efficient resource utilization, isolation, and deployment flexibility.

COMPANY NAME: PANTECH SOLUTION INDIA PRIVATE LIMITED

EVENT NAME: MOU COLLABORATION DATE: 17.12.2025

The Department of Computer Science & Engineering, Jeppiaar Institute of Technology, organized a Memorandum of Understanding (MoU) Signing Ceremony to strengthen Industry–Institute Collaboration with Pantech Solutions (India) Private Limited, T. Nagar, Chennai. The ceremony was held on Saturday, 20th December 2025, at the Jeppiaar Institute of Technology campus, Kunnam, Sunguvarchatram. The event marked an important milestone in fostering industry-oriented learning and collaborative academic initiatives. The MoU aims to facilitate industry-driven training programs, internships, workshops, technical seminars, certification courses, and real-time project exposure for students. This collaboration is expected to enhance students' technical competencies, professional skills, and readiness for industry challenges.